# R6013VND3

Nch 600V 250mohm(typ.) Power MOSFET

Datasheet

V <sub>DSS</sub> (@Tj max.)*5	650V
$R_{DS(on)}(Max.)$	0.300Ω
l <sub>DP</sub> *2	±39A
P <sub>D</sub>	131W

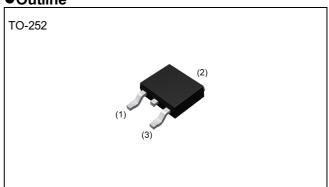
## Features

- 1) Fast reverse recovery time (trr)
- 2) Low on-resistance
- 3) Fast switching speed
- 4) Drive circuits can be simple
- 5) Pb-free plating; RoHS compliant
- 6) Halogen free mold compound

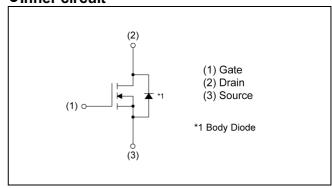
## Application

Switching applications

## Outline



## •Inner circuit



Marking	R6013VND3
Marking	11001011100

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	$V_{DSS}$	600	V
Continuous drain current (T <sub>c</sub> = 25°C)	I <sub>D</sub> *1	±13	Α
Pulsed drain current	l <sub>DP</sub> *2	±39	А
Gate - Source voltage	$V_{GSS}$	±30	V
Avalanche current, single pulse	I <sub>AS</sub>	1	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	55	mJ
MOSFET dv/dt	dv/dt*4	120	V/ns
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	131	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Downwortow	Cymah al	Values			1.1
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	0.95	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	50	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumb al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	600	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V	-	-	100	μA
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30 V, V_{DS} = 0 V$	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 0.5 \text{mA}$	4.5	5.5	6.5	V
Static drain - source	D *5	V <sub>GS</sub> = 15V, I <sub>D</sub> = 3A	-	0.250	0.300	Ω
on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3A	-	0.275	0.330	Ω
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	1.6	-	Ω

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davanastan	Cymah al	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 100V	-	900	-	
Output capacitance	C <sub>oss</sub>	f = 100kHz	-	45	-	
Effective output capacitance energy related	C <sub>o(er)</sub>	V <sub>GS</sub> = 0V	-	29	-	pF
Effective output capacitance time related	C <sub>o(tr)</sub>	V <sub>DS</sub> = 0V to 480V	-	188	1	
Turn - on delay time	t <sub>d(on)</sub> *5	V <sub>DD</sub> ≈ 300V, V <sub>GS</sub> = 15V	-	18	-	
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 3A	-	10	-	
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> ≃ 100Ω	-	46	-	ns
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	25	-	

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumb al	Conditions	Values			Lloit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≈ 300V	-	21	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 3A	-	7	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	10	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 300V$ , $I_D = 3A$	-	7.1	-	V

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Uill	
Source current	I <sub>S</sub> *1	- T <sub>C</sub> = 25°C	-	1	13	Α	
Pulsed source current	l <sub>SP</sub> *2		-	-	39	Α	
Source-Drain voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_{S} = 3A$	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *5	\/ ~ 400\/	-	65	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *5	- V <sub>DD</sub> ≃ 400V I <sub>S</sub> = 3A - di/dt = 100A/μs	-	190	-	nC	
Peak reverse recovery current	<sub>rr</sub> *5		-	6	-	Α	

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

<sup>\*3</sup> L $\rightleftharpoons$ 100mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , starting T<sub>i</sub>=25 $^{\circ}$ C

<sup>\*4</sup>  $V_{DS}$  = 0 to 400V

<sup>\*5</sup> Pulsed

<sup>\*6</sup>  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as Coss while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .

<sup>\*7</sup>  $C_{o(tr)}$  is a fixed capacitance that gives the same charging time as Coss while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .

## • Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

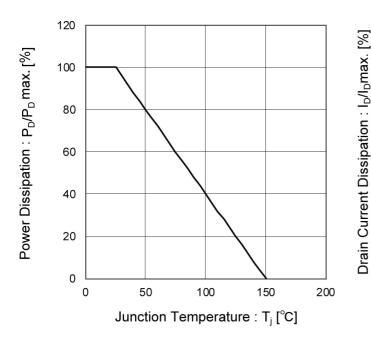


Fig.2 Drain Current Derating Curve

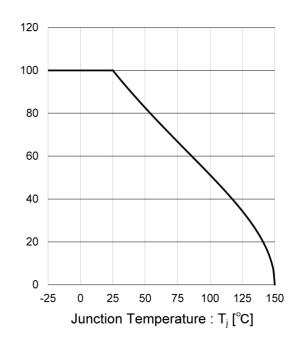


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

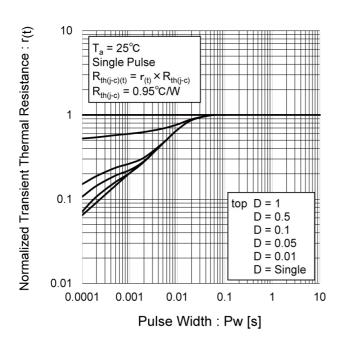
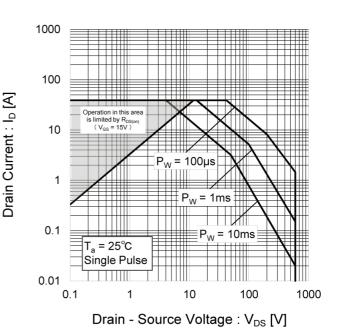


Fig.4 Maximum Safe Operating Area



## • Electrical characteristic curves

Fig.5 Avalanche Energy Derating Curve

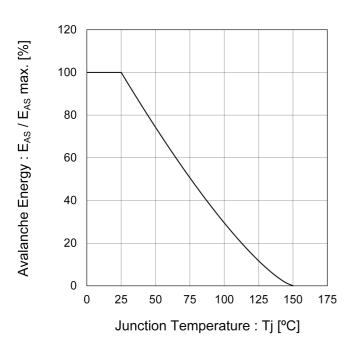


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

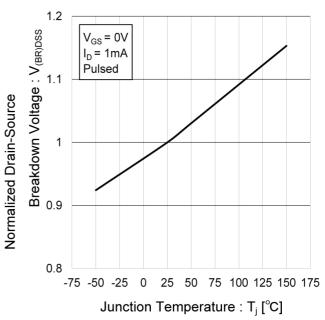


Fig.7 Output Characteristics(I)

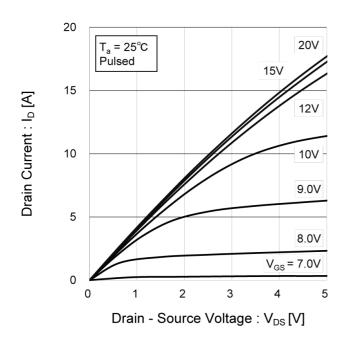
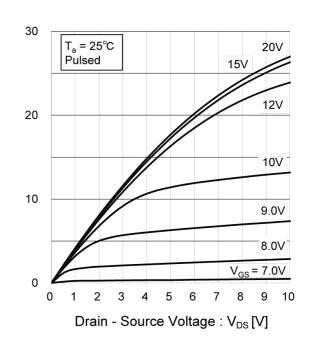


Fig.8 Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

#### Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs. Drain current

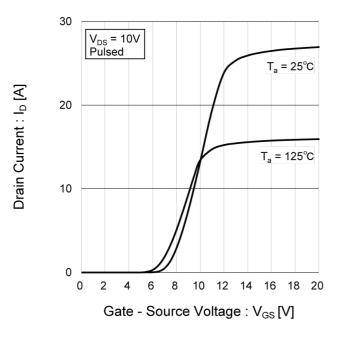


Fig.10 Normalized Gate Threshold Voltage vs. Junction Temperature

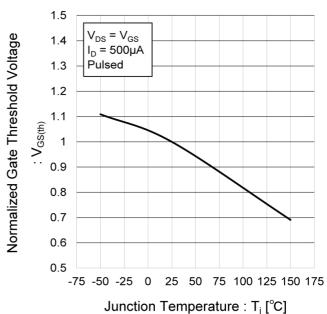


Fig.11 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

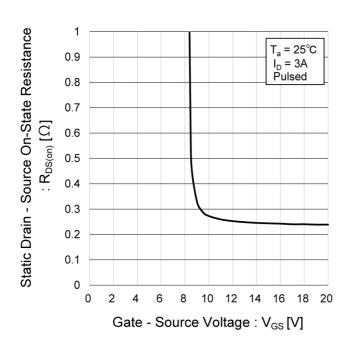
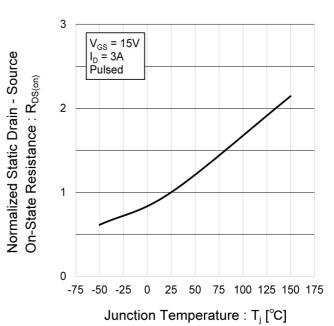


Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature



## Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Drain Current

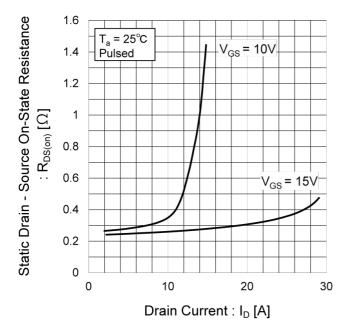


Fig.14 Capacitances

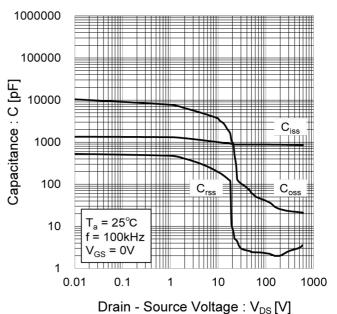


Fig.15 Coss Stored Energy

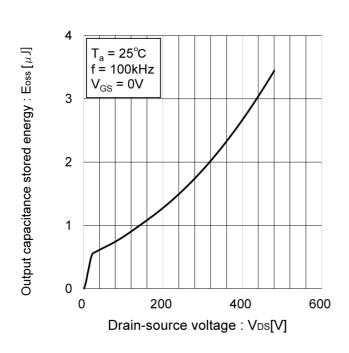
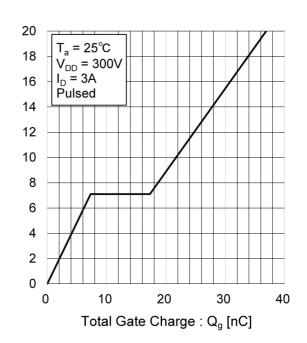


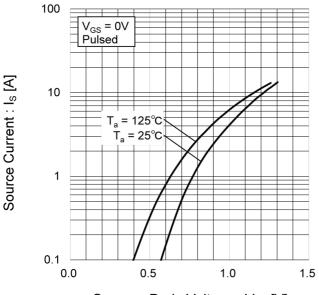
Fig.16 Gate Charge



Gate - Source Voltage :  $V_{GS}$  [V]

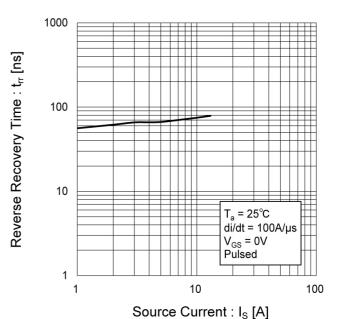
## • Electrical characteristic curves

Fig.17 Source Current vs. Source - Drain Voltage



Source - Drain Voltage : V<sub>SD</sub> [V]

Fig.18 Reverse Recovery Time vs. Source Current



## Measurement circuits

Fig.1-1 Switching time measurement circuit

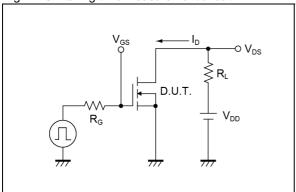


Fig.2-1 Gate charge measurement circuit

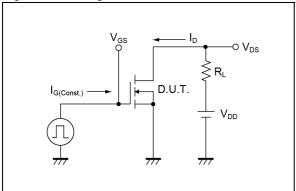


Fig.3-1 Avalanche measurement circuit

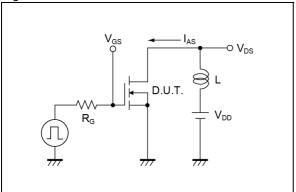


Fig.4-1 trr measurement circuit

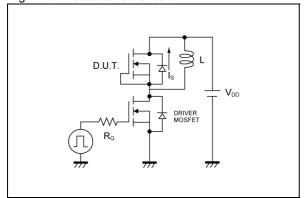


Fig.1-2 Switching waveforms

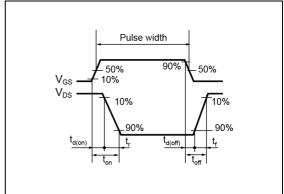


Fig.2-2 Gate charge waveform

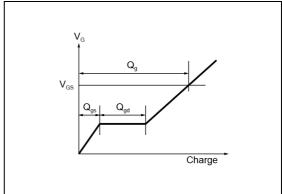


Fig.3-2 Avalanche waveform

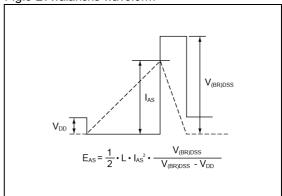
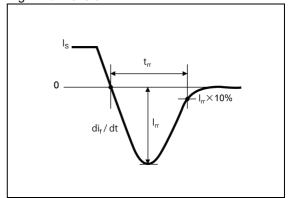
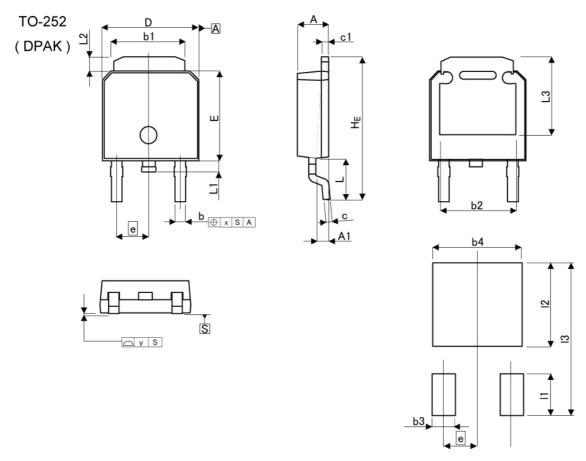


Fig.4-2 trr waveform



## Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	TERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	2.20	2.40	0.087	0.094		
A1	0.70	1.10	0.028	0.043		
b	0.60	0.90	0.024	0.035		
b1	5.20	5.50	0.205	0.217		
b2	4.	80	0.1	89		
С	0.40	0.60	0.016	0.024		
c1	0.40	0.60	0.016	0.024		
D	6.40	6.80	0.252	0.268		
е	2.30		0.0	91		
E	6.00	6.40	0.236	0.252		
HE	9.40	10.40	0.370	0.409		
L	2.	90	0.1	14		
L1	0.60	1.00	0.024	0.039		
L2	0.70	1.30	0.028	0.051		
L3	5.30		0.2	209		
Х	-	0.25	-	0.010		
у	-	0.10	, <del>-</del> ,	0.004		
DIM	MILIMETERS		RS INCHES		INCHES	
DIM	MIN	MAX	MIN	MAX		
b3	- 1	1.15	-	0.045		
b4	-	5.55	1 <del>.</del>	0.219		
l1	-	2.77	-	0.109		
12	-	5.50	-	0.217		
13	-	10.40	-	0.409		

Dimension in mm/inches



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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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For details, please refer to ROHM Mounting specification

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  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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